



Material Content Data Sheet



Halogen-Free

Sales Product Name	IDB18E120	Issued	11. August 2021
MA#	MA000520510		
Package	PG-TO263-3-2	Weight*	1558.94 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.293	0.21	0.21	2112	2112
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.50	19.53	195021	195275
wire	non noble metal	aluminium	7429-90-5	3.630	0.23	0.23	2329	2329
encapsulation	inorganic material	zinc oxide	1314-13-2	6.866	0.44		4404	
	miscellaneous	miscellaneous	-	27.463	1.76		17617	
	plastics	epoxy resin	-	102.988	6.61		66063	
	inorganic material	silicon dioxide	60676-86-0	549.268	35.24	44.05	352333	440417
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6194	6194
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.055			35	
	noble metal	silver	7440-22-4	0.069			44	
	non noble metal	lead	7439-92-1	2.621	0.17	0.17	1681	1760
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.13	35.18	351307	351765
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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